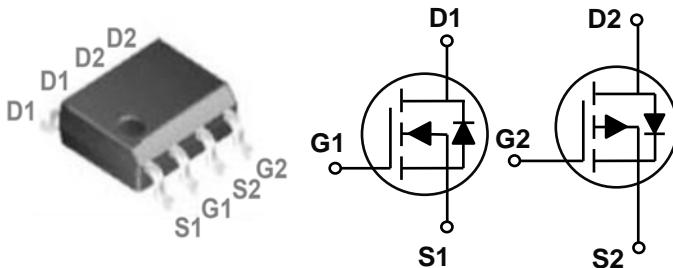


## 60V N+P Dual Channel MOSFETs

### General Description

These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOP-8 Pin Configuration



BVDSS	RDS(on)	ID
60V	54mΩ	4.5A
-60V	105mΩ	-3.5A

### Features

- Fast switching
- Green Device Available
- Suit for 4.5V Gate Drive Applications

### Applications

- DC Fan
- Motor Drive Applications
- Networking
- Half / Full Bridge Topology

### Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating		Units
$V_{DS}$	Drain-Source Voltage	60	-60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	4.5	-3.5	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	2.85	-2.21	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	18	-14	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	3.57		W
	Power Dissipation – Derate above 25°C	0.028		W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150		°C
$T_J$	Operating Junction Temperature Range	-55 to 150		°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{JA}$	Thermal Resistance Junction to ambient	---	75	°C/W
$R_{JC}$	Thermal Resistance Junction to Case	---	35	°C/W

## 60V N+P Dual Channel MOSFETs

N-CH Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	60	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.05	---	$\text{V}/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=60\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

### On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$ , $I_D=6\text{A}$	---	45	54	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=3\text{A}$	---	52	63	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	1.2	1.8	2.5	V
			---	-4.2	---	$\text{mV}/^\circ\text{C}$
$g_{fs}$	Forward Transconductance	$V_{DS}=10\text{V}$ , $I_D=4\text{A}$	---	4.2	---	S

### Dynamic and switching Characteristics

$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS}=30\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=4\text{A}$	---	14	21	nC
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		---	2.9	5	
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		---	2.3	4	
$T_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$V_{DD}=30\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=3.3\Omega$	---	3.9	7	ns
$T_r$	Rise Time <sup>2,3</sup>		---	12.6	24	
$T_{d(off)}$	Turn-Off Delay Time <sup>2,3</sup>		---	23.1	44	
$T_f$	Fall Time <sup>2,3</sup>		---	6.7	13	
$C_{iss}$	Input Capacitance	$V_{DS}=15\text{V}$ , $V_{GS}=0\text{V}$ , $F=1\text{MHz}$	---	800	1160	pF
$C_{oss}$	Output Capacitance		---	380	550	
$C_{rss}$	Reverse Transfer Capacitance		---	115	170	
$R_g$	Gate resistance	$V_{GS}=0\text{V}$ , $V_{DS}=0\text{V}$ , $F=1\text{MHz}$	---	1.7	3.4	$\Omega$

### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	4.5	A
			---	---	9	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

## 60V N+P Dual Channel MOSFETs

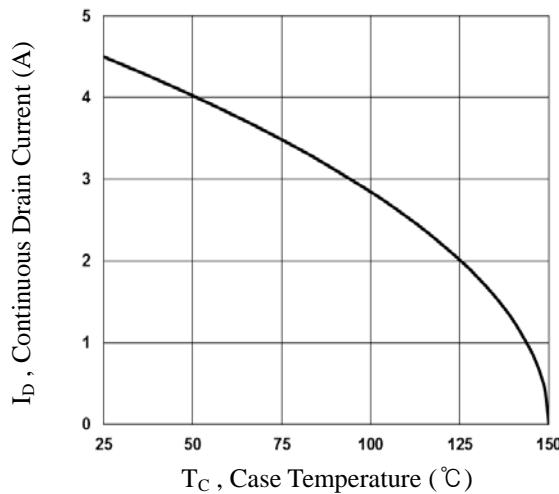


Fig.1 Continuous Drain Current vs.  $T_C$

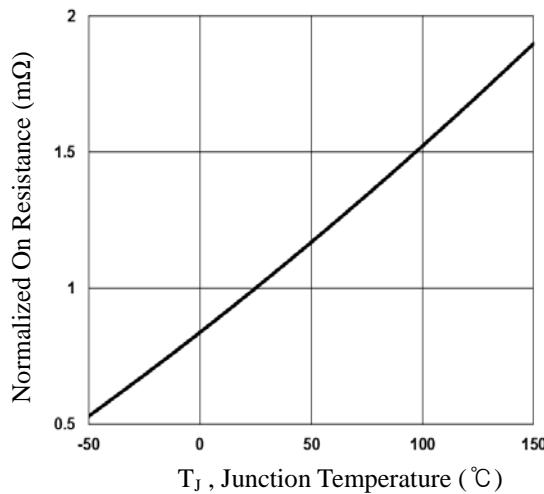


Fig.2 Normalized RDS(on) vs.  $T_J$

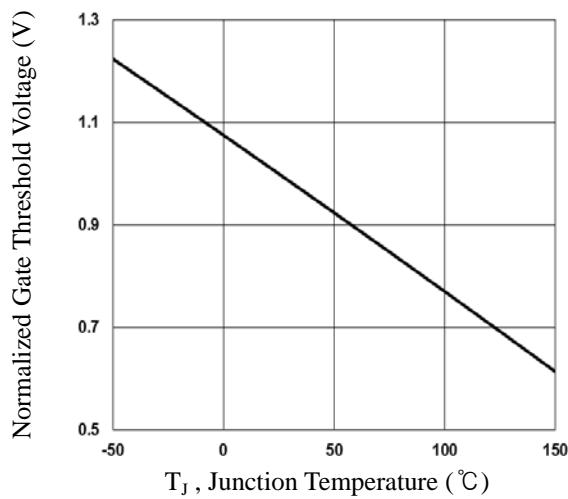


Fig.3 Normalized  $V_{th}$  vs.  $T_J$

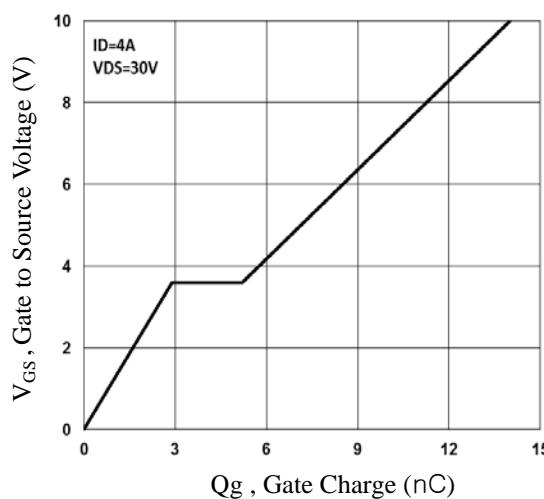


Fig.4 Gate Charge Waveform

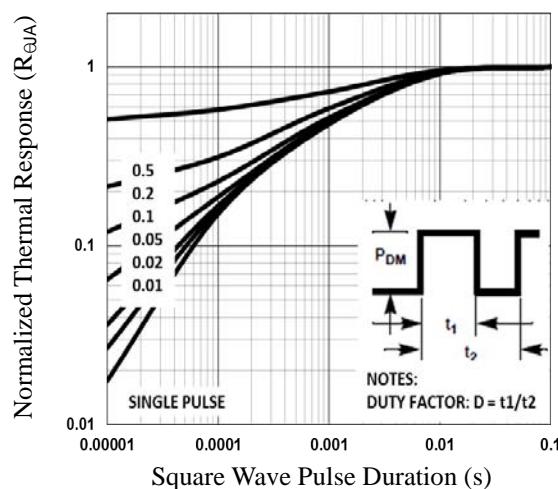


Fig.5 Normalized Transient Impedance

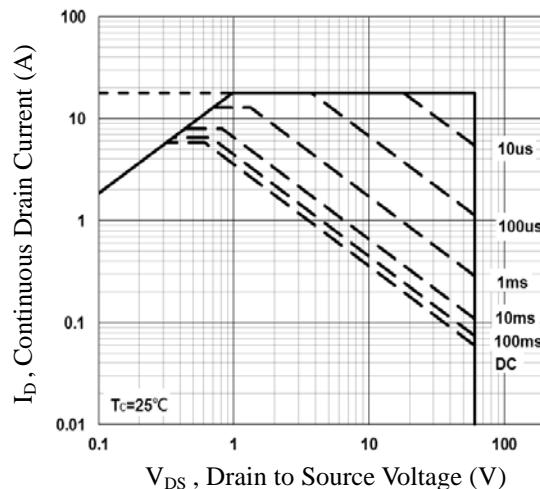


Fig.6 Maximum Safe Operation Area



# FTK6710

## 60V N+P Dual Channel MOSFETs

P-CH Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-60	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.05	---	$\text{V}/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-60\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu\text{A}$
		$V_{DS}=-48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	-10	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

### On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$ , $I_D=-6\text{A}$	---	87	105	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$ , $I_D=-3\text{A}$	---	120	145	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=-250\mu\text{A}$	-1.0	-1.6	-2.5	V
			---	3	---	$\text{mV}/^\circ\text{C}$
$g_{fs}$	Forward Transconductance	$V_{DS}=-10\text{V}$ , $I_D=-6\text{A}$	---	5.5	---	S

### Dynamic and switching Characteristics

$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS}=-30\text{V}$ , $V_{GS}=-10\text{V}$ , $I_D=-4\text{A}$	---	10	15	nC
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		---	1.6	3.2	
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		---	3	6	
$T_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$V_{DD}=-30\text{V}$ , $V_{GS}=-10\text{V}$ , $R_G=6\Omega$ $I_D=-1\text{A}$	---	8	16	ns
$T_r$	Rise Time <sup>2,3</sup>		---	15.4	30	
$T_{d(off)}$	Turn-Off Delay Time <sup>2,3</sup>		---	42.8	80	
$T_f$	Fall Time <sup>2,3</sup>		---	8.4	16	
$C_{iss}$	Input Capacitance	$V_{DS}=-30\text{V}$ , $V_{GS}=0\text{V}$ , $F=1\text{MHz}$	---	785	1300	pF
$C_{oss}$	Output Capacitance		---	175	300	
$C_{rss}$	Reverse Transfer Capacitance		---	112	220	

### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	-3.5	A
$I_{SM}$	Pulsed Source Current		---	---	-7	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_S=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1	V

Note :

4. Repetitive Rating : Pulsed width limited by maximum junction temperature.
5. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
6. Essentially independent of operating temperature.

## 60V N+P Dual Channel MOSFETs

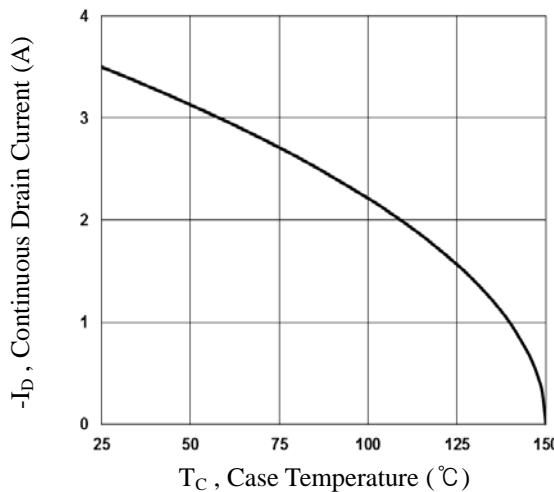


Fig. 7 Continuous Drain Current vs. T<sub>C</sub>

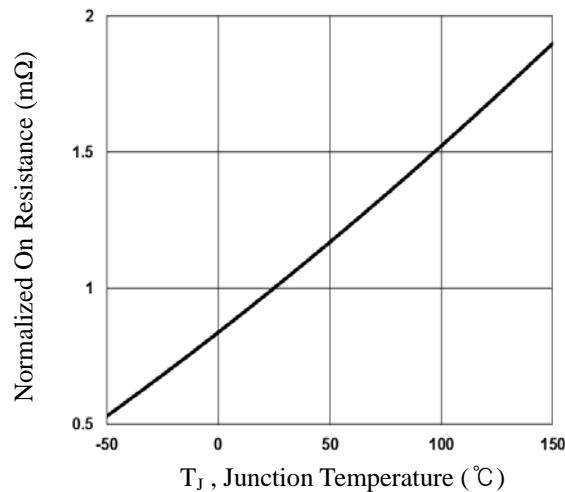


Fig. 8 Normalized RDS(on) vs. T<sub>J</sub>

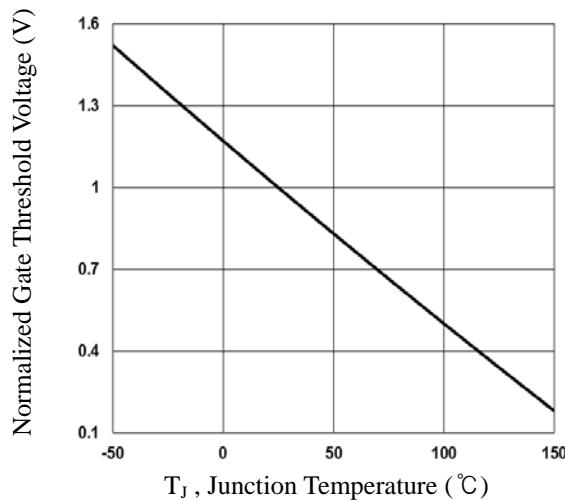


Fig. 9 Normalized V<sub>th</sub> vs. T<sub>J</sub>

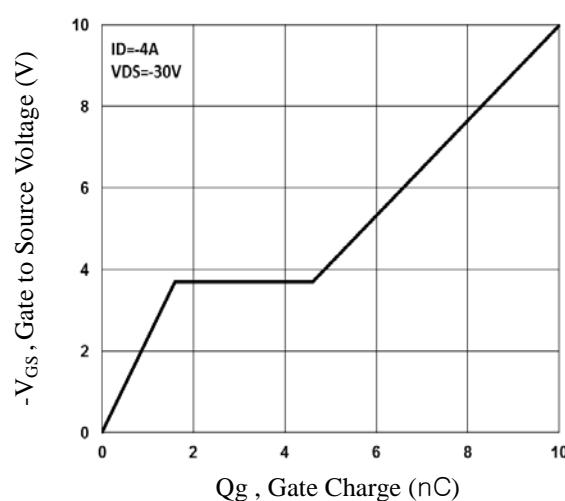


Fig. 10 Gate Charge Waveform

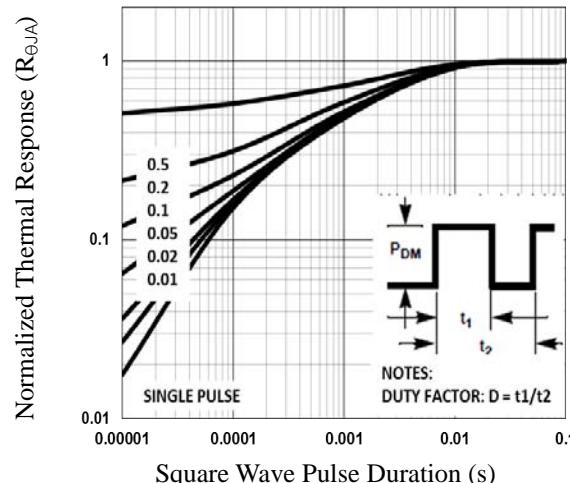


Fig. 11 Normalized Transient Impedance

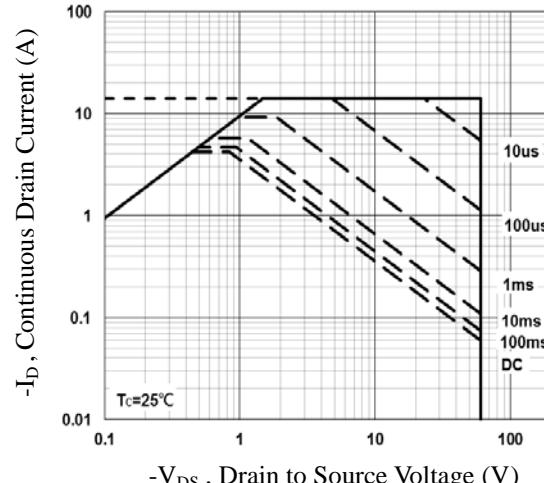
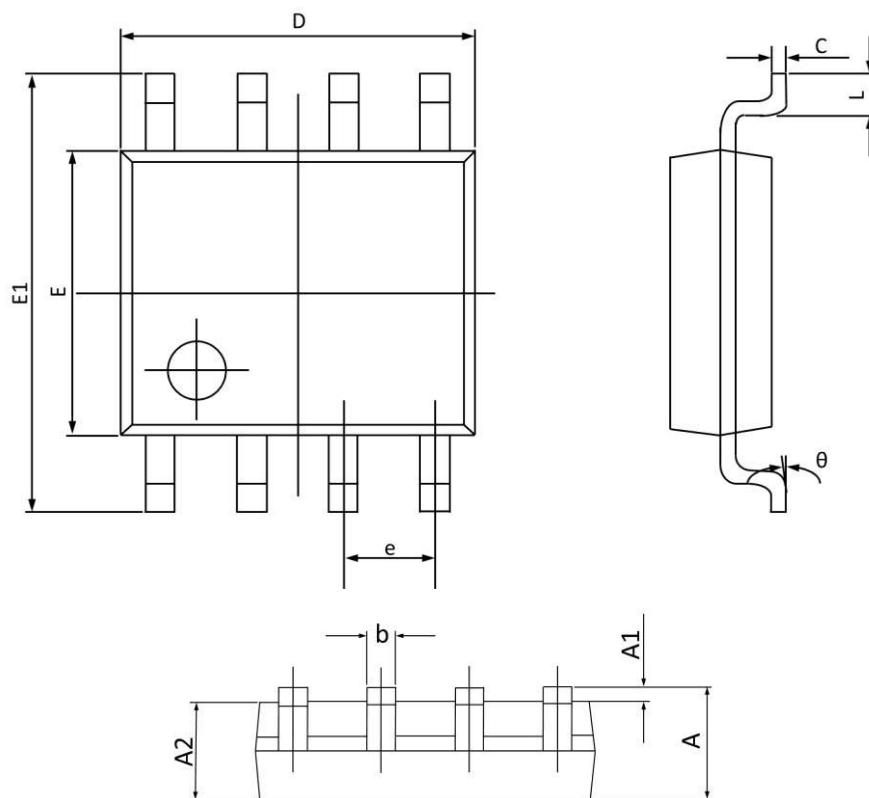


Fig. 12 Maximum Safe Operation Area

## 60V N+P Dual Channel MOSFETs

## SOP-8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.750	1.350	0.069	0.053
A1	0.250	0.100	0.010	0.004
A2	1.500	1.300	0.059	0.051
b	0.490	0.350	0.019	0.014
C	0.260	0.190	0.010	0.007
D	5.100	4.700	0.201	0.185
E	4.100	3.700	0.161	0.146
E1	6.200	5.800	0.244	0.228
e	1.27BSC		0.05BSC	
L	0.900	0.400	0.035	0.016
θ	8°	0°	8°	0°